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(54) Title: A METHOD AND DEVICE FOR ALIGNING COMPONENTS

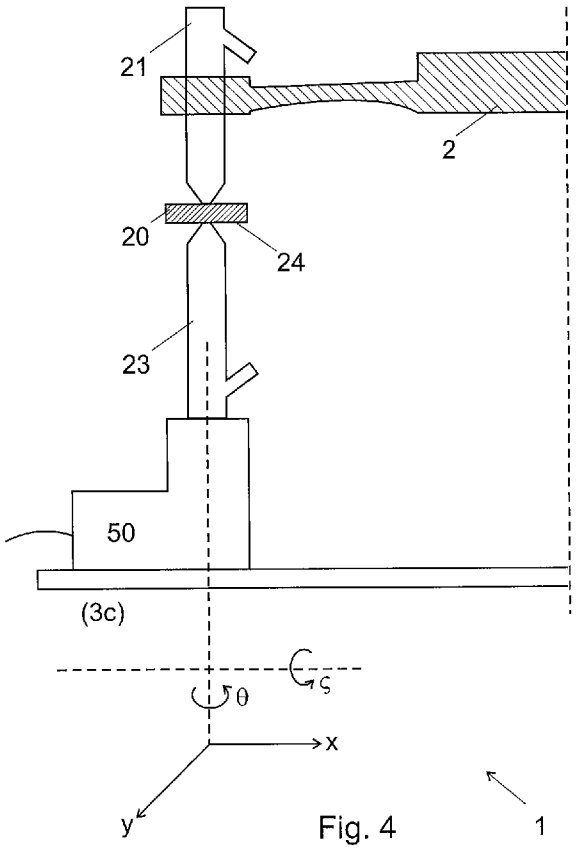


Fig. 4

(57) Abstract: Method and apparatus for aligning a small-size component with vacuum pick-up nozzles within turrets used with electronic components or assembly equipments. The method comprises the steps of picking-up the component with a pick-up nozzle; measuring a position of the component in respect to a defined value; bringing the component held by the pick-up nozzle in contact with a aligning device; holding the component with the aligning device and; moving the aligning device in order to align the component based on the position measurement.

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